IPC ASSOCIATION ELECTRONICS	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				laterials and	ials and Mfg Information			
upplier	· Information													
ompany	name*	Company unique ID			Ţ	Unique ID Authority				Response Date*				
nsemi											2023-06-08			
ontact Na	ame	Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-E	Env-Stewards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
uthorized	d Representative*	Title - Representative			I	Phone - Representative*			Email	Email - Representative*				
roduct-E	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number		Mfr Item Number Mfr Item Name		e		Effective Date	Version	Manufacturing Si	Manufacturing Site		UOM	Unit Type	
		LM2575T-12G ANA 12V 1A PWR		R SW REG		2023-06-08		MY1	MY1		mg	Each		
-	cturing Process Informa		Camaia al Dana	A11	-STD-020 MS	U Datina	Deele Dee	D. J. T.	Mar Time 4	Deel Terre	Ni	of Deflect Co		
	, , , , , , , , , , , , , , , , , , ,		Terminal Base Alloy J-STE CU Alloy NA			L Rating	Peak Process Body Temperature Max Time :		Peak Temperature Number of Reflow Cycle seconds 3		cies			
	` '		O Alloy	I	(A		U	<u> </u>	30	seco	mus [3			
omments														
	information regarding materia		1 6 4											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.55	mg	Supplier	Silicon (Si)	7440-21-3		3.55	mg
Die Attach	82.83	mg	A	Lead (Pb)	7439-92-1	7a	78.6885	mg
			Supplier	Tin (Sn)	7440-31-5		4.1415	mg
Lead Frame	1297.64	mg	Supplier	Copper (Cu)	7440-50-8		1297.64	mg
Mold Compound-Black	543.9			Epoxy resin	proprietary data		38.073	mg
			Supplier	Phenolic Resin	Proprietary Data		38.073	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		81.585	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7195	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		383.4495	mg
Plating	31.13	mg	Supplier	Tin (Sn)	7440-31-5		31.13	mg
Wire Bond - Cu	1.37	mg	Supplier	Copper (Cu)	7440-50-8		1.37	mg